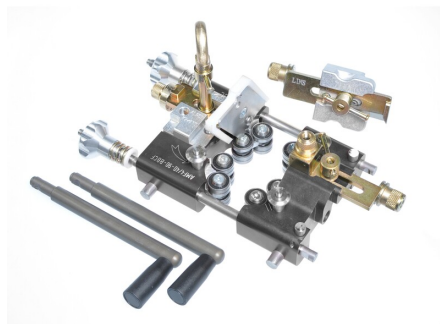




See online
technical sheet

/ CAMF4/40-90-BBCF

Multifunction tool for bonded semiconductor and insulation



/ Use

CAMF SERIE tools enable the user to :

- remove the bonded semiconductor
- remove the insulation

Bonded semiconductor removal : very steady (16 ball bearings around the cable), shaping the cable round over the insulation, constant diameter over the insulation, prevent the blade from digging into the insulation

Insulation removal : back-iron that enables the user to tune the pitch of the tool thus making the rotation of the tool easy when removing the insulation

/ Advantages

- No silicon needed
- Smooth finish
- Robust design
- Counter-iron to regulate tool feed and facilitate rotation
- Motorised option
- Cable rounding
- Adjustment of the tool feed (chip thickness)
- Reduces sanding time - AC Insulator
- Rugosité minimale sur isolant (DC)
- All-in-one capability - K7 (K7/GNS, K7/PNS, K7/CH)

/ Areas of activity

-  Cable & Connections
-  Industry
-  Production

/ Technical specifications

- Specific tools : Cable tools
- Cable tools : Cable tools
- For network cables : HTB
- Height (mm) : 150
- Weight (kg) : 3,9
- Max diameter (mm) : 90
- Mini diameter (mm) : 40
- Cut deepness (mm) : 35
- Remining length of semi conductor (MIN) (mm) : 55
- Scoring depth MAX (mm) : 2,5
- Lenght (mm) : 460
- Width (mm) : 155
- Packaging : Case

/ Accessories

	Reference	Designation
	ET-AMF4	Motorization for AMF4

/ Spare parts

	Reference	Designation
	LFNS	LFNS
	LINS	LINS

/ Associated products

	Reference	Designation
	GRI	Scraper for semiconductor residues
	CHN2/25-60-NS	Alrocone tool to taper shape on insulation without silicone
	DMSR/40-90	Stripping tool for HV and EHV cable's outer sheath and shield